

**Amendments to the Claims:**

This listing of claims will replace all prior versions and listings of claims in the application.

**Listing of Claims:**

Please amend claims 4-5 and 8-9 and cancel claims 1-3 without prejudice or disclaimer so that the current status of all claims is as follows:

- 1-3. (canceled)
4. (currently amended) An infrared data communication module comprising:  
a substrate having a surface provided with a die bonding pad ~~formed by plating that~~ includes a conductive film and a gold layer formed on the conductive film by plating the film with gold [ , ]; and  
a light emitting element mounted on the die bonding pad [ , ];  
wherein the die bonding pad being is generally circular as viewed in plan and having an area larger than a bottom surface area of the light emitting element, the gold layer of the pad being exposed for reflecting light emitted from the light emitting element.
5. (currently amended) An infrared data communication module comprising:  
a substrate having a surface for mounting a light emitting element, a light receiving element and an IC element;  
a protective member for covering each of the elements; and  
a molded body formed of a molding resin on said surface of the substrate to cover the protective member;  
wherein said surface of the substrate being is formed with a recess for enhancing bond bonding between the substrate and the molded body, the recess being completely filled with part of the molded body alone.
6. (original) The infrared data communication module according to claim 5, wherein the recess is formed on said surface of the substrate at each of plural portions which avoid the protective member.

7. (previously presented) The infrared data communication module according to claim 5, wherein the recess is generally cylindrical.

8. (currently amended) A method of making infrared data communication modules, each of which comprises a substrate having a surface for mounting a group of components which includes a light emitting element, a light receiving element and an IC element, and a molded body formed of a molding resin to entirely cover said surface of the substrate for sealing the group of components, said surface of the substrate being formed with at least one jumper pad formed by plating a conductive film with gold, the method comprising the steps of:

forming a conductive film on an entire surface of a material board including substrate areas which later provide substrates;

etching the conductive film to form a plating conductive pattern which later provides jumper pads;

applying a gold foil on the plating conductive pattern by electroplating at jumper pad regions which correspond to the jumper pads;

removing a connecting portion of the plating conductive pattern extending from an edge of each substrate area to outside of the substrate area;

mounting groups of elements;

shaping a molding ~~rein~~ resin into molded bodies on the material board; and

dividing the material board along each of the substrate areas.

9. (currently amended) A method of making an infrared data communication module which comprises a substrate having a surface for mounting a group of components including a light emitting element, a light receiving element and an IC element, and a molded body formed of a molding resin to seal the group of components, the method comprising the steps of:

forming a recess on said surface of the substrate for enhancing ~~bond~~ bonding between the substrate and the molded body before the group of components is mounted on the substrate; and

forming the molded body so that the molding resin is trapped and hardened in the recess after the group of components is mounted on the substrate, the recess being completely filled with the molding resin alone.